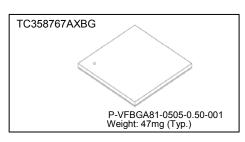
CMOS Digital Integrated Circuit Silicon Monolithic

TC358767AXBG

Mobile Peripheral Devices

Overview

TC358767AXBG is a bridge device that enables video streaming from a Host (application or baseband processor) over MIPI® DSI or DPI link to drive DisplayPort™ display panels. TC358767AXBG also supports audio streaming from the host via I2S interface to the Display panels. TC358767AXBG provides a low power bridge solution to efficiently translate MIPI® DSI or DPI transfers to DisplayPort™ transfers. As the



DisplayPortTM uses fewer wires compared to other existing display panel standards, it simplifies the LCD connectivity. The effect of using TC358767AXBG is to enable existing baseband devices supporting DSI or DPI streaming to connect to new panels supporting DisplayPortTM interface and also to connect to existing panels over longer distance using DisplayPortTM adaptors at far-end. TC358767AXBG can interface to up to two independent devices.

Features

- Translates MIPI[®] DSI/DPI Link video stream from Host to DisplayPortTM Link data to external display devices.
- The inputs are driven by a DSI Host with 4-Data Lanes, upto1 Gbps/lane or DPI Host with 16/18/24 bit interface upto154 MHz parallel clock
- Supports HDCP Digital Content Protection version 1.3 (DisplayPort[™] amendment Rev1.1).
- Embeds audio information from the I2S port into the DisplayPort[™] data stream.
- The output Interface consists of a DisplayPort[™] Tx with a 2-lane Main Link and AUX-Ch.
- Register Configuration: From DSI link or I²C interface.
- Interrupt to host to inform any error status or status needing attention from Host.
- Internal test pattern (color bar) generator for DP o/p testing without any video (DSI/DPI) i/p.
- Debug/Test Port: I²C Slave

DSI Receiver

- → MIPI® DSI: v1.01 / MIPI® D-PHY: v0.90 Compliant.
- ♦ Up to four (4) Data Lanes with Bi-direction support on Data Lane 0.
- ♦ Maximum speed at 1 Gbps/lane.
- Supports Burst as well as Non-Burst Mode Video Data.
 - Video data packets are limited to one row per Hsync period.
- Supports video stream packets for video data transmission.
- Supports generic long packets for accessing the chip's register set.

- Video input data formats:
- RGB-565, RGB-666 and RGB-888.
- New DSI V1.02 Data Type Support: 16-bit YCbCr 422
- ♦ Interlaced video mode is not supported.

DPI Receiver

- ♦ Up to 16 / 18 / 24 bit parallel data interface.
- ♦ Maximum speed at 154 MPs (MPixel per sec).
- ♦ Video input data formats: RGB-565, RGB-666 and RGB-888.
- ♦ Only Progressive mode supported.
- I2S Audio Interface: Supports one I2S port for audio streaming from the host to TC358767AXBG.
- Supports slave mode (BCLK, LRCLK & over-sampling clock input from Host).
- ♦ Supports sampling frequencies of 32, 44.1, 48, 88.2, 96, 176.4 & 192 kHz.
- ♦ Supports up to 2 audio channels.
- ♦ Supports 16, 18, 20 or 24bits per sample.
- Optionally inserts IEC60958 status bits and preamble bits per channel.
- DisplayPort[™] Interface: Supports a
 DisplayPort[™] link from TC358767AXBG to
 display panels.
- → High speed serial bridge chip using VESA DisplayPort™ 1.1a Standard.
- ♦ Supports one dual-lane DisplayPortTM port for high bandwidth applications
- ♦ Support 1.62 or 2.7 Gbps/lane data rate with voltage swings @0.4, 0.6, 0.8 or 1.2 V
- Support of pre-emphasis levels of 0, 3.5dB and 6dB.



- Supports Audio related Secondary Data Packets.
- ♦ AUX channel supported at 1 Mbps.
- ♦ HPD support through GPIO[0] based interrupts
- Enhanced mode supported for content protection.
- Support HDCP encryption Version 1.3 with DisplayPort™ amendment Revision 1.1.
- Secure ASSR (Alternate Scrambler Seed Reset) support for eDP panels
 - System designer connects ASSR_DisablePad to VSS to enable eDP panels and ASSR
- Drive ASSR_DisablePad with an inner ring VDDS for using DP panels and disable ASSR
- System software read Revision ID field, 0x0500[7:0]:
 - Ox01 indicates eDP panels are used, DPCD register bit 0x0010A[0] of eDP panel should be set
 - ➤ 0x03 assumes DP panels are connected, DPCD register bit 0x0010A[0] of DP panel should Not be set
- Stream Policy Maker is assumed handled by the Host (software/firmware).
 - Start Link training in response to HPD & read final Link training status
- Configure DP link for actual video streaming & start video streaming
- Link Policy maker is assumed shared between the Host and TC358767AXBG chip.
- In auto_correction = 0 mode, control link training
- Initiate Display device capabilities read and configure TC358767AXBG accordingly.
- Video timing generation as per panel requirement.
- ♦ SSCG with to 30 kHz modulation to reduce EMI.
- → Toshiba Magic Square algorithm RGB666 18b produces RGB888 24b like quality (with up to 16-million colors).
- ♦ Built in PRBS7 Generator to test DisplayPortTM Link.

• RGB Parallel Output Interface:

- → RGB888 output (DisplayPortTM disabled) with only DSI input supported in this mode
- ♦ PCLK max. = 100 MHz
- Polarity control for PCLK, VSYNC, HSYNC & DE

• I²C Interface:

- I²C slave interface for chip register set access enabled using a boot-strap option.
- ♦ I²C compliant slave interface support for normal (100 kHz) and fast mode (400 kHz).

GPIO Interface:

- ♦ 2 bits of GPIO (shared with other digital logic).
- ♦ Direction controllable by Host I²C accesses.

Clock Source:

- → DisplayPortTM clock source is from an external clock input or clock from DSI interface (13, 26, 19.2 or 38.4 MHz) – generates all internal & output clocks to interfacing display devices.
- → Built-in PLLs generate high-speed DisplayPortTM link clock requiring no external components. These PLLs are part of the DisplayPortTM PHY.
- Clock and power management support to achieve low power states.

• Possible modes of Operation:

- → MODE S21: TC358767AXBG uses DisplayPortTM Tx as single 2-lane DisplayPortTM link to interface to single DisplayPortTM display device. Video stream source is from MIPI[®] DSI Host.
- → MODE P21: TC358767AXBG uses DisplayPortTM Tx as single 2-lane DisplayPortTM link to interface to single DisplayPortTM display device. Video stream source is from MIPI[®] DPI Host.
- → MODE S2P: TC358767A uses only Parallel output port and disables DisplayPortTM Tx to interface to single RGB display device. Video stream source is from MIPI® DSI Host.

• Power supply inputs

- ♦ Core and MIPI® D-PHY: 1.2 V ± 0.06 V
- ♦ Digital I/O: 1.8 V ± 0.09 V
- ♦ DisplayPortTM: $1.8 \text{ V} \pm 0.09 \text{ V}$ ♦ DisplayPortTM: $1.2 \text{ V} \pm 0.06 \text{ V}$

Power Consumptions (based on estimations)

♦ Power-down mode (DSI-Rx in ULPS, DP PHY & PLLs disabled, clocks stopped):

- DSI Rx: 0.01 mW - DP PHY: 2.34 mW - PLL9: 0.01 mW - Core: 0.96 mW - Rest: 0.01 mW

♦ Normal operation (1920 × 1080 resolution with DSI-Rx in 4-lane @925 Mbps per lane, DP PHY in dual lane link @2.7 Gbps per lane):

DSI Rx: 21.79 mW
 DP PHY: 142.70 mW
 PLL9: 2.42 mW
 Core: 87.64 mW
 IOs: 1.68 mW

Package

0.5mm ball pitch, 81 balls, 5 × 5 mm BGA package



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REFERENCES

- 1. MIPI® DSI, "MIPI® Alliance Specification for DSI Version 1.01.00 21 February 2008"
- 2. MIPI® DPI, "MIPI® Alliance Standard for Display Pixel Interface (DPI-2) Version 2.00 15 September 2005"
- 3. MIPI® D-PHY, "DRAFT MIPI® Alliance Specification for D-PHY Version 0.91.00 r0.01 14-March-2008"
- 4. VESA DisplayPort™ Standard (Version 1, Revision 1A January 11, 2008)
- VESA Embedded DisplayPortTM (eDP) Standard (Version 1.1 October 23, 2009)
 Digital Content Protection LLC, HDCP (Version 1.3 with DisplayPortTM amendment Revision 1.1, Jan. 15 2010)
- 7. I²C bus specification, version 2.1, January 2000, Philips Semiconductor
- 8. Draft CEA-861-C, A DTV Profile for Uncompressed High Speed Digital Interfaces (Doc. Number: CEA-861rCv9.pdf (PNXXX)) Date: 05/04/2005
- 9. DisplayPort[™] PHY DFT Strategy Specification Rev 1.3

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1. Overview

The DSI/DPI to DisplayPortTM converter (TC358767AXBG) is a bridge device that enables video streaming from a Host (application or baseband processor) over MIPI® DSI or DPI link to drive DisplayPortTM display panels. TC358767AXBG also supports audio streaming from the host via I2S interface to the Display panels. TC358767AXBG provides a low power bridge solution to efficiently translate MIPI® DSI or DPI transfers to DisplayPortTM transfers. As the DisplayPortTM uses fewer wires compared to other existing display panel standards, it simplifies the LCD connectivity. The effect of using TC358767AXBG is to enable existing baseband devices supporting DSI or DPI streaming to connect to new panels supporting DisplayPortTM interface and also to connect to existing panels over longer distance using DisplayPortTM adaptors at far-end. TC358767AXBG can interface to up to two independent devices.

The chip can be configured through the DSI link by sending write/read register commands through DSI Generic Long Write packets. It can also be configured through the I²C Slave interface.

The DSI-RX receiver supports from 1 to 4-Lane configurations at bit rate up to 1 Gbps per lane. Host can transmit video in continuous video streaming mode. Host controls video timing by sending video frame and line sync events together with video pixel data; video data transmission can be burst or non-burst. Since the chip integrates only a small video buffer, Host still has to take care of transmitting pixel data at appropriate video line time in order to avoid buffer overflow (or underflow).

The DPI-Rx receiver supports 16, 18 or 24 bits parallel interface along with the required control signals for the Pixel clock and HSync/VSync/DE.

The TC358767AXBG also supports content protection using HDCP copy protection. (Option)
The DisplayPortTM transmitter supports data throughput at 1.62 Gbps or 2.7 Gbps per lane of main link.
TC358767AXBG supports three configuration modes. These modes mainly differ based on the source of input stream and number of display devices that TC358767AXBG can be connected to.

- Mode_S21: A system configuration where TC358767AXBG may typically be used is shown in Figure 1.1. In this configuration, the TC358767AXBG can support displays with resolution up to WUXGA (1920×1200) at 24bit, 60 fps or WUXGA (1920×1200) at 18bit, 60 fps. Video stream source is from DSI Host.
- Mode_P21: A system configuration where TC358767AXBG may typically be used is shown in Figure 1.2. This is similar to the Mode_S21 except that the video stream source is from DPI Host. In this configuration, the TC358767AXBG can support displays with resolution up to WUXGA (1920×1200) at 24bit, 60 fps.
- Mode_S2P: A system configuration where TC358767AXBG may typically be used is shown in Figure 1.3. In this mode, DisplayPort™ output is not used and the chip rather behaves as a DSI to RGB convertor. In this system, TC358767AXBG could be connected to a single display. In this configuration, the TC358767AXBG can support displays with resolution up to WXGA (1280x800 or 1366x768). Max. output PCLK is 100MHz. Video stream source is from DSI Host.



The chip supports power management to conserve power when its functions are not in use. Host manages the chip's power consumption modes by using ULPS messages over DSI link during DPI input mode.

The following figures show all these modes, where TC358767AXBG, display panels and a Host are connected in target Reference system for mobile large display panel applications.

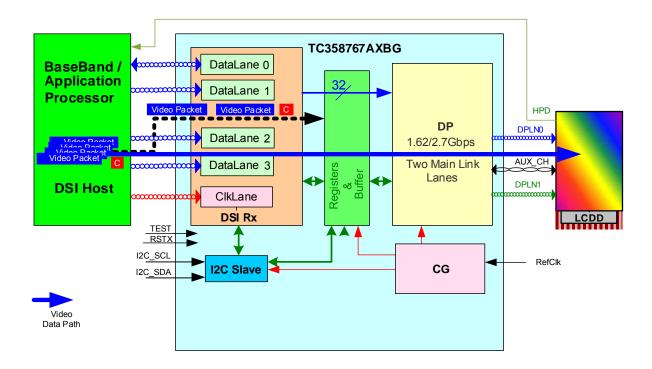


Figure 1.1 System Overview with TC358767AXBG in MODE_S21 Configuration

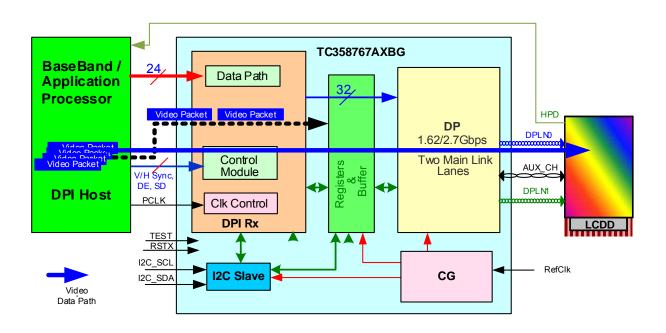


Figure 1.2 System Overview with TC358767AXBG in MODE_P21 Configuration

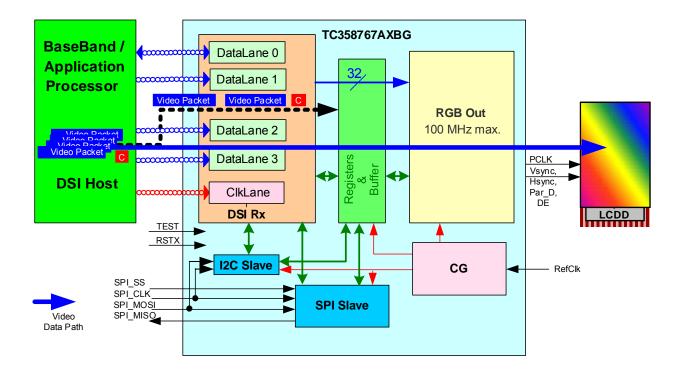


Figure 1.3 System Overview with TC358767AXBG in MODE_S2P Configuration



2. Features

Below are the main features supported by TC358767AXBG.

- Translates MIPI[®] DSI/DPI Link video stream from Host to DisplayPort[™] Link data to external display devices.
- The inputs are driven by a DSI Host with 4-Data Lanes, upto1 Gbps/lane or DPI Host with 16/18/24 bit interface upto154 MHz parallel clock.
- Supports HDCP Digital Content Protection version 1.3 (DisplayPort[™] amendment Rev1.1).
- Embeds audio information from the I2S port into the DisplayPortTM data stream.
- The output Interface consists of a DisplayPortTM Tx with a 2-lane Main Link and AUX-Ch.
- Register Configuration: From DSI link or I²C interface.
- Interrupt to host to inform any error status or status needing attention from Host.
- Internal test pattern (color bar) generator for DP o/p testing without any video (DSI/DPI) i/p.
- Debug/Test Port: I2C Slave

DSI Receiver

- ♦ MIPI® DSI: v1.01 / MIPI® D-PHY: v0.90 Compliant.
- ♦ Up to four (4) Data Lanes with Bi-direction support on Data Lane 0.
- ♦ Maximum speed at 1 Gbps/lane.
- ♦ Supports Burst as well as Non-Burst Mode Video Data.
 - Video data packets are limited to one row per Hsync period.
- ♦ Supports video stream packets for video data transmission.
- ♦ Supports generic long packets for accessing the chip's register set.
- ♦ Video input data formats:
 - RGB-565, RGB-666 and RGB-888.
 - New DSI V1.02 Data Type Support: 16-bit YCbCr 422
- → Interlaced video mode is not supported.

DPI Receiver

- ♦ Up to 16 / 18 / 24 bit parallel data interface.
- ♦ Maximum speed at 154 MPs (MPixel per sec).
- ♦ Video input data formats: RGB-565, RGB-666 and RGB-888.
- ♦ Only Progressive mode supported.
- I2S Audio Interface: Supports one I2S port for audio streaming from the host to TC358767AXBG.
 - ♦ Supports slave mode (BCLK, LRCLK & over-sampling clock input from Host).
 - ♦ Supports sampling frequencies of 32, 44.1, 48, 88.2, 96, 176.4 & 192 kHz.
 - ♦ Supports up to 2 audio channels.
 - → Supports 16, 18, 20 or 24 bits per sample.
 - ♦ Optionally inserts IEC60958 status bits and preamble bits per channel.
- DisplayPort[™] Interface: Supports a DisplayPort[™] link from TC358767AXBG to display panels.
 - ♦ High speed serial bridge chip using VESA DisplayPortTM 1.1a Standard.
 - ♦ Supports one dual-lane DisplayPort[™] port for high bandwidth applications.
 - ♦ Support 1.62 or 2.7 Gbps/lane data rate with voltage swings @0.4, 0.6, 0.8 or 1.2 V.
 - ♦ Support of pre-emphasis levels of 0, 3.5 dB and 6 dB.
 - ♦ Supports Audio related Secondary Data Packets.
 - ♦ AUX channel supported at 1 Mbps.
 - ♦ HPD support through GPIO[0] based interrupts
 - ♦ Enhanced mode supported for content protection.
 - ♦ Support HDCP encryption Version 1.3 with DisplayPort™ amendment Revision 1.1.
 - ♦ Secure ASSR (Alternate Scrambler Seed Reset) support for eDP panels
 - System designer connects ASSR DisablePad to VSS to enable eDP panels and ASSR
 - Drive ASSR_DisablePad with an inner ring VDDS for using DP panels and disable ASSR
 - System software read Revision ID field, 0x0500[7:0]:
 - > 0x01 indicates eDP panels are used, DPCD register bit 0x0010A[0] of eDP panel should be set
 - 0x03 assumes DP panels are connected, DPCD register bit 0x0010A[0] of DP panel should Not be set.



- ♦ Stream Policy Maker is assumed handled by the Host (software/firmware).
 - Start Link training in response to HPD & read final Link training status
 - Configure DP link for actual video streaming & start video streaming
- ♦ Link Policy maker is assumed shared between the Host and TC358767AXBG chip.
 - In auto correction = 0 mode, control link training
 - Initiate Display device capabilities read and configure TC358767AXBG accordingly.
- ♦ Video timing generation as per panel requirement.
- ♦ SSCG with to 30 kHz modulation to reduce EMI.
- → Toshiba Magic Square algorithm RGB666 18b produces RGB888 24b like quality (with up to 16-million colors).
- ♦ Built in PRBS7 Generator to test DisplayPort™ Link.

• RGB Parallel Output Interface:

- ♦ RGB888 output (DisplayPort[™] disabled) with only DSI input supported in this mode
- ♦ PCLK max. = 100 MHz
- ♦ Polarity control for PCLK, VSYNC, HSYNC & DE

• I2C Interface:

- ♦ I²C slave interface for chip register set access enabled using a boot-strap option.
- ♦ I²C compliant slave interface support for normal (100 kHz) and fast mode (400 kHz).

• GPIO Interface:

- ♦ 2 bits of GPIO (shared with other digital logic).
- ♦ Direction controllable by Host I²C accesses.

Clock Source:

- → DisplayPortTM clock source is from an external clock input or clock from DSI interface (13, 26, 19.2 or 38.4 MHz) generates all internal & output clocks to interfacing display devices.
- ♦ Built-in PLLs generate high-speed DisplayPortTM link clock requiring no external components. These PLLs are part of the DisplayPortTM PHY.
- Clock and power management support to achieve low power states.

• Possible modes of Operation:

- ♦ MODE S21: TC358767AXBG uses DisplayPortTM Tx as single 2-lane DisplayPortTM link to interface to single DisplayPortTM display device. Video stream source is from MIPI[®] DSI Host.
- ♦ MODE P21: TC358767AXBG uses DisplayPortTM Tx as single 2-lane DisplayPortTM link to interface to single DisplayPortTM display device. Video stream source is from MIPI[®] DPI Host.
- ♦ MODE S2P: TC358767AXBG uses only Parallel output port and disables DisplayPortTM Tx to interface to single RGB display device. Video stream source is from MIPI® DSI Host.

Power supply inputs

- ♦ Core and MIPI® D-PHY: 1.2 V ± 0.06 V
- ♦ Digital I/O: 1.8 V ± 0.09 V
- ♦ DisplayPortTM: 1.8 V ± 0.09 V
- ♦ DisplayPortTM: 1.2 V ± 0.06 V

Power Consumptions (based on estimations)

♦ Power-down mode (DSI-Rx in ULPS, DP PHY & PLLs disabled, clocks stopped):

- DSI Rx: 0.01 mW - DP PHY: 2.34 mW - PLL9: 0.01 mW - Core: 0.96 mW - Rest: 0.01 mW

♦ Normal operation (1920×1080 resolution with DSI-Rx in 4-lane @925 Mbps per lane, DP PHY in dual lane link @2.7 Gbps per lane):

DSI Rx: 21.79 mW
 DP PHY: 142.70 mW
 PLL9: 2.42 mW
 Core: 87.64 mW
 IOs: 1.68 mW

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Package

- 0.5mm ball pitch, 81 balls, 5 × 5 mm BGA package

Note: Attention about ESD. This product is weak against ESD. Please handle it carefully.

Table 2.1 TC358767AXBG operational modes summary with panel size support information

Mode	Input Confi	figuration Register Access		Max Panel
Wode	DSI input	DPI input	Method	size example
S21	Active	Х	DSI or I ² C	WUXGA 18bpp @ 60fps WUXGA 24bpp @ 60fps
P21	X	Active	I ² C	WUXGA 24bpp @ 60fps

Tables below provide an idea of different panel sizes that can be supported by using different data link lane configurations.

Table 2.2 Panel Size v/s Data link required by TC358767AXBG in DSI input case

	Frame Size			Dissel		RGB6	66			RGB	888	
		With OverHead	FPS	Pixel Clock (MHz)	Bit Rate	# DSI Data	# DP l linl		Bit Rate	# DSI Data	# DP Ma	in links
		Overnead		(1411 12)	(Gbps)	lanes	1.62G	2.7G	(Gbps)	lanes	1.62G	2.7G
XGA	1024×768	1184×790	60	56	1.01	2	1	1	1.34	2	2	1
WXGA+	1366×768	1526×790	60	72	1.30	2	2	1	1.74	2	2	1
WXGA+ / WSXGA	1440×900	1600×926	60	89	1.60	2	2	1	2.13	3	2	1
SXGA+	1400×1050	1560×1080	60	89	1.82	2	2	1	2.43	3	2	2
WSXGA+	1680×1050	1840×1080	60	119	2.15	3	2	1	2.86	3	_	2
UXGA	1600×1200	1760×1235	60	130	2.35	3	2	2	3.13	4	_	2
WUXGA	1920×1200	2080×1235	60	154	2.77	3	_	2	3.70	4	_	2

Table 2.3 Panel Size v/s Data link required by TC358767AXBG in DPI input case

	Frame Size			Pixel DPI Support	R	RGB666			RGB888		
		With OverHead	FPS	Clock (MHz)	154 MHz PCLK	Bit Rate	# DP lin		Bit Rate		Main ıks
		Overnead		(1411 12)	FOLK	(Gbps)	1.62G	2.7G	(Gbps)	1.62G	2.7G
XGA	1024×768	1184×790	60	56	Yes	1.01	1	1	1.34	2	1
WXGA+	1366×768	1526×790	60	72	Yes	1.30	2	1	1.74	2	1
WXGA+ / WSXGA	1440×900	1600×926	60	89	Yes	1.60	2	1	2.13	2	1
SXGA+	1400×1050	1560×1080	60	89	Yes	1.82	2	1	2.43	2	2
WSXGA+	1680×1050	1840×1080	60	119	Yes	2.15	2	1	2.86	_	2
UXGA	1600×1200	1760×1235	60	130	Yes	2.35	2	2	3.13	_	2
WUXGA	1920×1200	2080×1235	60	154	Yes	2.77	_	2	3.70	_	2

Note: These are the formats commonly used by displays. Support for other sizes is possible as long

as they satisfy the maximum data rate constraints on the DSI and DisplayPort^{†M} link interfaces.

Note: Throughout the rest of the document, "DP" is used to denote "DisplayPort™". Both these words have been used interchangeably and refer to the VESA DisplayPort™

specification as mentioned in the references.



3. External Pins

3.1. TC358767AXBG External Pins

TC358767AXBG uses an 81pin package. Following table gives the signals of TC358767AXBG and their function.

Table 3.1 TC358767AXBG Functional Signal List for 81-pin Package

Group	Pin Name	I/O	Туре	Function	Note	
	RESX	ı	Sch	System Reset – active Low		
	REFCLK	ı	Sch	13, 26, 19.2 or 38.4 MHz		
Cyatamy	_	ı	3011	50ps phase jitter p2p/ WC duty cycle 40-60%		
System: Reset &	TEST	- 1	N	Test Pin, active high	_	
Clock	TEST[3]	0	Ν	Test Pin, Open	_	
(9)	INT	0	N	Interrupt to Host	4mA	
(3)	DISABLE_ASSR	I	N	Disable ASSR, set when connecting to DP panels Enable ASSR for eDP panel application	_	
	MODE[1:0]	ı	N	Mode Selection pins	_	
	DSICP	ı	MIPI-PHY	MIPI®-DSI Rx Clock Lane Pos	_	
DSI Rx	DSICM	ı	MIPI-PHY	MIPI®-DSI Rx Clock Lane Neg	_	
(10)	DSIDP[3:0]	I/O	MIPI-PHY	MIPI®-DSI Rx Data Lane Pos	_	
	DSIDM[3:0]	I/O	MIPI-PHY	MIPI®-DSI Rx Data Lane Neg	_	
	DPLNP[1:0]	0	DP-PHY	eDP Output Main Link Pos	_	
DD 04	DPLNM[1:0]	0	DP-PHY	eDP Output Main Link Neg	_	
DP Out	DPAUXP[0]	I/O	DP-PHY	eDP Output AUX Channel Pos	_	
(8)	DPAUXM[0]	I/O	DP-PHY	eDP Output AUX Channel Neg	_	
	PREC_RES[1:0]	ı	DP-PHY	Precision Resistance (3K @ 1%) connection	_	
	DPI PCLK	I/O	N	DPI Pixel Clock (max 154 MHz) (default: Input)	4mA	
5515	DPI VSYNC	I/O	N DPI Vertical Sync (default: Input)		4mA	
DPI RX	DPI HSYNC	I/O	N	DPI Horizontal Sync (default: Input)	4mA	
(28)	DPI DE	I/O	N DPI Data Enable (default: Input)			
	DPI D [23:0]	I/O	N	DPI Parallel Data (default: Input)	4mA	
100	I2C_SCL	OD	FS/Sch	I ² C Clock	_	
I2C	I2C SDA	OD	FS/Sch	I ² C Data	4mA	
(3)	I2C ADR SEL	I	N	I ² C Slave Address Select	_	
	I2S OSCLK	I	N	I2S Over Sampling Clock	_	
I2S	I2S BCLK	I	N	I2S Bit Clock (max 12.5 MHz)	_	
(4)	I2S_LRCLK	I	N	I2S sample clock (max 192 kHz)	_	
	I2S_DATA	ı	N	I2S Data		
GPIO (2)	GPIO[1:0]	OD	5T-OD	GPIO or Test Control *Note1 GPIO[1:0] can be used for HPD support	4mA	
	VDDC (VDD12)	NA	ı	VDD for Internal Core (2)	_	
	VDDS (1.8V)	NA		VDDS for IO Ring power supply (1)	_	
	VDD_PLL18 (1.8V)	NA	_	VDD for DP PHY PLLs (1)	_	
POWER	VDD_PLL12 (1.2V)	NA	_	VDD for DP PHY PLLs (1)	_	
	VDD_DP18 (1.8V)	NA		VDD for DP PHY Main Channels (2)	_	
(11)	VDD_PLL912 (1.2V)	NA	_	VDD for PLL9 (1)		
	VDD_DP12 (1.2V)	NA		VDD for DP PHY (1)		
	VDD_DSI12 (1.2V)	NA		VDD for the MIPI® DSI PHY (1)	_	
	VPGM	NA		eFUSE programming voltage (1)		
GROUND	1/00			Ground (including VSSC (core), VSS_IO (IO), VSS_DSI	_	
(7)	VSS	NA	_	(MIPI®), VSS_DP (DP))	_	

Total 81 pins TC358767AXBG BGA package.

Note 1: Pins with multiplexed Functional mode functions

N: Normal IO FS: Fail safe IO - gated PHY: Either DP analog front end or MIPI® D-PHY Sch: Schmitt trigger input

OD: Open drain 5T-OD: 5 V tolerant bi-direction buffer with Open drain

Pd: Pull Down



3.2. TC358767AXBG Pin Mapping

The mapping of TC358767AXBG signals to the external pins is given in the following figure. (BGA array)

Top View (through the die)

A1	A2	А3	A4	A5	A6	A7	A8	A9
AI	AZ	A3	A4	Ab	Ao	Α/	A8	A9
DSIDM_0	DSIDP_0	I2S_LRCLK	VDDC	VDDC	INT	VDDS	I2C_SDA	I2C_SCL
B1	B2	В3	В4	B 5	В6	В7	В8	В9
DSIDM_1	DSIDP_1	GPIO_0	I2S_BCLK	I2S_DATA	MODE_0	MODE_1	GPIO_1	I2C_ADR_SEL
C1	C2	С3	C4	C5	C6	С7	С8	С9
DSICM	DSICP	DPI_DE	DPI_VSYNC	DPI_D_5	DPI_D_7	DPI_D_10	TEST_3	I2S_OSCLK
D1	D2	D3	D4	D5	D6	D7	D8	D9
VDD_DSI12	VSS_DSI	DPI_HSYNC	DPI_D_0	VSS	DPI_D_9	DPI_D_12	DPI_D_13	DSI_D_14
E1	E2	E3	E4	E 5	E6	E7	E8	E9
DSIDM_2	DSIDP_2	DPI_D_1	DPI_D_3	VSS	VSS	DPI_D_16	VPGM_0	DPI_D_11
F1	F2	F3	F4	F5	F6	F7	F8	F9
DSIDM_3	DSIDP_3	DPI_D_2	DPI_D_6	DPI_D_8	DPI_D_15	DPI_D_18	DPI_D_17	DPI_D_20
G1	G2	G3	G4	G5	G6	G7	G8	G9
PREC_RES_0	Disable_ASSR	DPI_D_4	TEST	DPI_D_19	DPI_PCLK	DPI_D_21	DPI_D_23	DPI_D_22
Н1	H2	Н3	Н4	Н5	Н6	Н7	Н8	Н9
PREC_RES_1	VSS_DP	DPLNP_0	VDD_DP12	VSS_DP	DPLNP_1	VSS_DP	DPAUXP_0	VDD_PLL912
J1	J2	J3	J4	J5	J6	J7	78	J9
REFCLK	VDD_DP18	DPLNM_0	VDD_PLL12	VDD_PLL18	DPLNM_1	VDD_DP18	DPAUXM_0	RESX

Figure 3.1 TC358767AXBG 81-Pin Layout

Table 3.2 Mechanical Dimension of TC358767AXBG BGA

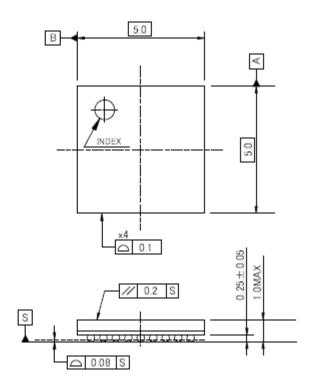
Package	Solder Ball Pitch	Solder Ball Height	Package Dimension	Package Height	Note
81-Pin	0.5 mm	0.25 mm	5.0 × 5.0 mm ²	1.0 mm	_



4. Package

The package for TC358767AXBG is described in the figure below.

P-VFBGA81-0505-0.50-001 "Unit.mm"



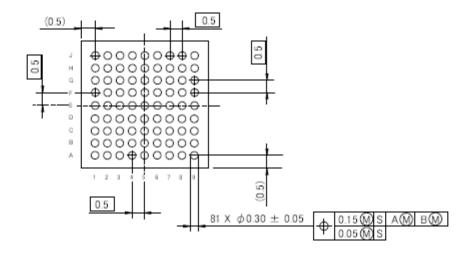


Figure 4.1 81 pin TC358767AXBG package

Weight: 47 mg (Typ.)



The mechanical dimension of BGA81 package is listed below.

Table 4.1 Mechanical Dimension of P-VFBGA81-0505-0.50-001

Package	Solder Ball Pitch	Solder Ball Height	Package Dimension	Package Height	Note
81-Pin	0.50 mm	0.25 mm	5.0 × 5.0 mm ²	1.0 mm	1



5. Electrical Characteristics

5.1. Absolute Maximum Ratings

VSS = 0 V reference

VDD18 used for VDDS as well as VDD-DP18; VDD12 used for VDDC as well as VDD-DSI12

Table 5.1 Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage (1.8 V)	VDD18	-0.3 to +3.5	V
Supply voltage (1.2 V)	VDD12	-0.3 to +2.0	V
Supply voltage (IO)	VDD18	-0.3 to +3.5	V
Supply voltage (IO)	VREF	-0.3 to +3.5	V
Input voltage	VIN	-0.3 to VDDS+0.3	V
Output voltage	VOUT	-0.3 to VDDS+0.3	V
Storage temperature	Tstg	-40 to +125	°C

5.2. Operating Condition

VSS = 0 V reference

VDD18 used for VDDS as well as VDD-DP18; VDD12 used for VDDC as well as VDD-DSI12

Table 5.2 Operating Condition

Parameter	Symbol	Min	Тур.	Max	Unit
Supply voltage (1.8 V)	VDD18	1.71	1.8	1.89	V
Supply voltage (1.2 V)	VDD12	1.14	1.2	1.26	V
Operating frequency (internal)	Fopr	_	_	200	MHz
Operating temperature	Та	-20	_	+85	°C



5.3. DC Electrical Specification

VSS = VSS_C = VSS_IO = VSS_DSI = VSS_DP = VSS_PLL = VSS_REG = 0V reference

Table 5.3 DC Electrical Specification

Parameter	Symbol	Min	Тур.	Max	Unit
Input voltage High level CMOS input Note1	VIH	0.7 VDDS	_	VDDS	V
Input voltage Low level CMOS input Note1	VIL	0	_	0.3 VDDS	V
Input voltage High level CMOS Schmitt Trigger Note1	VIHS	0.7 VDDS	_	VDDS	V
Input voltage Low level CMOS Schmitt Trigger Note1	VILS	0	_	0.3 VDDS	V
Output voltage High level Note1, Note2	VOH	0.8 VDDS	_	VDDS	V
Output voltage Low level Note1, Note2	VOL	0	_	0.2 VDDS	V
Input leak current High level	IIH1 (Note3)	-10	_	10	μΑ
Input look current Low lovel	IIL1 (Note4)	-10	_	10	μΑ
Input leak current Low level	IIL2 (Note5)	-200	_	-10	μΑ

Note1: VDDS within recommended operating condition.

Note2: Output current value is according to each IO buffer specification. Output voltage changes with output current value.

Normal pin, or Pull-up I/O pin applied VDD18_IO supply voltage to input pin Note3:

Note4: Normal pin applied VSS (0 V) to input pin Note5: Pull-up I/O pin applied VSS (0 V) to input pin

5.4. Power Consumption

Power consumption as measured for the power-down modes and for normal operation are provided below:

Power-down mode (DSI-Rx in ULPS, DP PHY & PLLs disabled, clocks stopped):

DSI Rx: 0.01 mW ♦ DP PHY: 2.34 mW ♦ PLL9: 0.01 mW ♦ Core: 0.96 mW Rest: 0.01 mW

Normal operation (1920×1080 resolution with DSI-Rx in 4-lane @925 Mbps per lane, DP PHY in dual lane link @2.7 Gbps per lane):

♦ DSI Rx: 21.79 mW ♦ DP PHY: 142.70 mW ♦ PLL9: 2.42 mW Core: 87.64 mW ♦ IOs: 1.68 mW

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6. Revision History

Table 6.1 Revision History

Revision	Date	Description
0.97	2014-04-10	Newly released
0.972	2016-04-01	Modified the weight of TC358767AXBG's package by rounding up digits after the decimal point to form an integer.
1.30	2017-07-10	Changed header, footer and the last page. Added Figure 1.3 and modified descriptions in section 1. Modified descriptions in Features and section 2. Modified Table 3.1 and Figure 3.1. Added Table numbers in section 5.
1.31	2017-12-27	Modified Figure 1.1, Figure 1.2, Figure 1.3. Changed frequency to 100MHz in Figure 1.3. Added description, trademarks and registered trademarks.



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